

ON Semiconductor®

FDS6890A

Dual N-Channel 2.5V Specified PowerTrench™ MOSFET

General Description

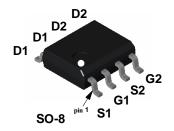
These N-Channel 2.5V specified MOSFETs are produced using ON Semiconductor's advanced PowerTrench process that has been especially tailored to minimize the on-state resistance and yet maintain low gate charge for superior switching performance.

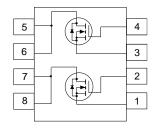
Applications

- DC/DC converter
- Motor drives

Features

- 7.5 A, 20 V. $R_{DS(ON)} = 0.018~\Omega~$ @ $V_{GS} = 4.5~V$ $R_{DS(ON)} = 0.022~\Omega~$ @ $V_{GS} = 2.5~V.$
- Low gate charge (23nC typical).
- Fast switching speed.
- High performance trench technology for extremely low $R_{\scriptscriptstyle DS(ON)}$.
- High power and current handling capability.





Absolute Maximum Ratings TA=25°C unless otherwise noted

Symbol	Parameter		Ratings	Units
V _{DSS}	Drain-Source Voltage		20	V
V _{GSS}	Gate-Source Voltage		±8	V
I _D	Drain Current - Continuous	(Note 1a)	7.5	А
	- Pulsed		20	
P _D	Power Dissipation for Dual Operation		2.0	W
	Power Dissipation for Single Operation	(Note 1a)	1.6	
		(Note 1b)	1.0	
		(Note 1c)	0.9	
T _J , T _{stg}	Operating and Storage Junction Temperature Range		-55 to +150	°C

Thermal Characteristics

$R_{\theta}JA$	Thermal Resistance, Junction-to-Ambient	(Note 1a)	78	°C/W
R _e JC	Thermal Resistance, Junction-to-Case	(Note 1)	40	°C/W
			90	

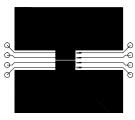
Package Marking and Ordering Information

Device Marking	Device	Reel Size	Tape Width	Quantity
FDS6890A	FDS6890A	13	12mm	2500 units

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Char	acteristics					
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	20			V
<u>ΔBV_{DSS}</u> ΔT _J	Breakdown Voltage Temperature Coefficient	I_D = 250 μ A, Referenced to 25°C		14		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 16 V, V _{GS} = 0 V			1	μΑ
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 8 V, V _{DS} = 0 V			100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = -8 V, V _{DS} = 0 V			-100	nA
On Char	acteristics (Note 2)					
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	0.5	0.8	1.5	V
$\Delta V_{GS(th)} \over \Delta T_J$	Gate Threshold Voltage Temperature Coefficient	I_D = 250 μ A, Referenced to 25°C		-3.5		mV/°C
R _{DS(on)}	Static Drain-Source On-Resistance	$\begin{aligned} &V_{GS} = 4.5 \text{ V, } I_D = 7.5 \text{ A} \\ &V_{GS} = 4.5 \text{ V, } I_D = 7.5 \text{ A, } T_J = 125^{\circ}\text{C} \\ &V_{GS} = 2.5 \text{ V, } I_D = 6.5 \text{ A} \end{aligned}$		0.013 0.021 0.016	0.018 0.034 0.022	Ω
I _{D(on)}	On-State Drain Current	V _{GS} = 10 V, V _{DS} = 5 V	20			Α
G FS	Forward Transconductance	V _{DS} = 5 V, I _D = 7.5 A		35		S
Dvnamio	Characteristics		•		•	•
C _{iss}	Input Capacitance	$V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V},$		2130		pF
Coss	Output Capacitance	f = 1.0 MHz		545		pF
C _{rss}	Reverse Transfer Capacitance	1		270		pF
Switchir	ng Characteristics (Note 2)			•		
t _{d(on)}	Turn-On Delay Time	$V_{DD} = 10 \text{ V}, I_{D} = 1 \text{ A}, \ V_{GS} = 4.5 \text{ V}, R_{GEN} = 6 \Omega$		13	24	ns
t _r	Turn-On Rise Time			26	42	ns
t _{d(off)}	Turn-Off Delay Time	1		65	90	ns
t _f	Turn-Off Fall Time	1		23	37	ns
Qg	Total Gate Charge	$V_{DS} = 10 \text{ V}, I_{D} = 7.5 \text{ A},$ $V_{GS} = 4.5 \text{ V},$		23	32	nC
Q _{gs}	Gate-Source Charge			3.2		nC
Q _{gd}	Gate-Drain Charge	7		4.4		nC
Drain-So	ource Diode Characteristics	and Maximum Ratings			-	•
I _S	Maximum Continuous Drain-Source				1.3	Α
V _{SD}	Drain-Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_S = 1.3 \text{ A}$ (Note 2)		0.65	1.2	V
				_		_

Notes:

 $\textbf{1.} \ \ \mathsf{R}_{\theta\mathsf{JA}} \ \mathsf{is} \ \mathsf{the} \ \mathsf{sum} \ \mathsf{of} \ \mathsf{the} \ \mathsf{junction} \mathsf{-to} \mathsf{-case} \ \mathsf{and} \ \mathsf{case} \mathsf{-to} \mathsf{-ambient} \ \mathsf{thermal} \ \mathsf{resistance} \ \mathsf{where} \ \mathsf{the} \ \mathsf{case} \ \mathsf{thermal} \ \mathsf{reference} \ \mathsf{is} \ \mathsf{defined} \ \mathsf{as} \ \mathsf{the} \ \mathsf{solder} \ \mathsf{mounting}$ surface of the drain pins. $R_{\theta JC}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design.





a) 78° C/W when mounted on a 0.5 in² pad of 2 oz. copper.

b) 125° C/W when mounted on a 0.02 in² pad of 2 oz. copper.

c) 135° C/W when mounted on a mounted on a minimum pad.



Scale 1 : 1 on letter size paper

Typical Characteristics (continued)

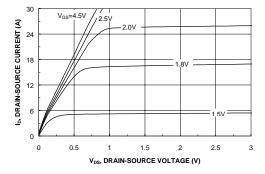


Figure 1. On-Region Characteristics.

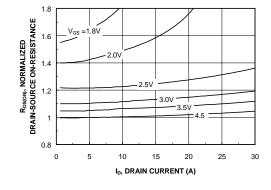


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

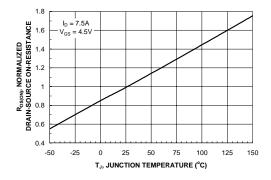


Figure 3. On-Resistance Variation with Temperature.

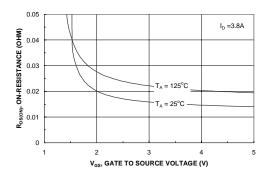


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

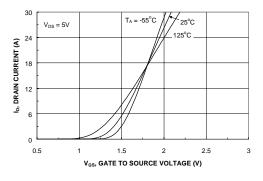


Figure 5. Transfer Characteristics.

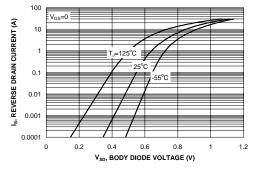
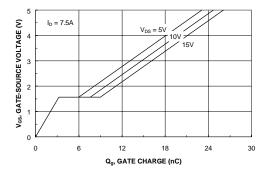


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

Typical Characteristics (continued)



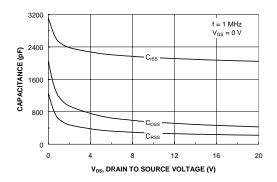
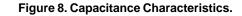
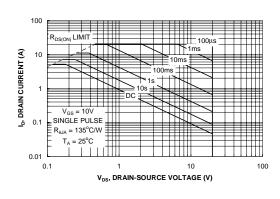


Figure 7. Gate Charge Characteristics.





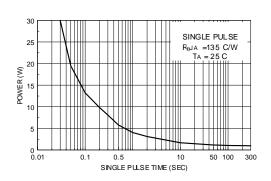


Figure 9. Maximum Safe Operating Area.

Figure 10. Single Pulse Maximum Power Dissipation.

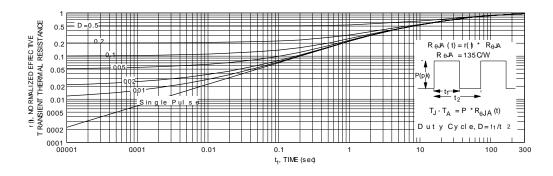


Figure 11. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1c. Transient themal response will change depending on the circuit board design.

ON Semiconductor and in are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hol

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com N. American Technical Support: 800-282-9855 Toll Free USA/Canada Europe, Middle East and Africa Technical Support: Phone: 421 33 790 2910

Phone: 421 33 790 2910

Japan Customer Focus Center
Phone: 81–3–5817–1050

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative